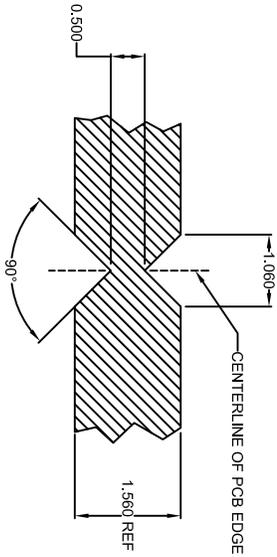


CROSS-SECTION
SUBSTRATE

CUSTOMER NOTICE		CONTRACT NO.			1530 Inducity Blvd. Milpitas, CA 95035-1099 Phone: 408 243-5077 Fax: 408 243-5077 LTC Confidential - For Customer Use Only
LINEAR TECHNOLOGY HAS MADE A BEST EFFORT TO DESIGN A CIRCUIT THAT MEETS CUSTOMER-SUPPLIED SPECIFICATIONS; HOWEVER, IT REMAINS THE CUSTOMER'S RESPONSIBILITY TO VERIFY PROPER AND RELIABLE OPERATION IN THE ACTUAL APPLICATION. COMPONENT SUBSTITUTION AND PRINTED CIRCUIT BOARD LAYOUT MAY SIGNIFICANTLY AFFECT CIRCUIT PERFORMANCE OR RELIABILITY. CONTACT LINEAR TECHNOLOGY APPLICATIONS ENGINEERING FOR ASSISTANCE.		PCB DES. GRIFFITHS ENG. D. STUETZLE			
THIS CIRCUIT IS PROPRIETARY TO LINEAR TECHNOLOGY AND SUPPLIED FOR USE WITH LINEAR TECHNOLOGY PARTS.		SIZE	IC NO.	14-Bit, 125 Msps Quad ADC with Integrated Drivers	REV
		B	DEMOCIRCUIT DC1732B	LTM19012-AB	0
		DATE:	Monday, December 12, 2011	SHEET	12 OF 15

NOTES: UNLESS OTHERWISE SPECIFIED.

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. VIA WALL COPPER THICKNESS TO BE 0.030 MIN.
3. PLATING: IMMERSION GOLD BOTH SIDES.
 NI - 0.003 MINIMUM TO 0.005 MAXIMUM.
 AU - 0.0001 MINIMUM TO 0.0003 MAXIMUM.
4. PCB TO BE ELECTRICALLY TESTED. USE CAPTURED GERBER DATA PROVIDED.
5. DELETED.
6. CORE MATERIAL - FR4, 4 LAYER, 1oz Cu INTERNAL LAYERS, 1oz Cu + PLATING EXTERNAL LAYERS
7. SOLDERMASK - LPI, GREEN, BOTH SIDES. POSITIONAL TOLERANCE = +/-0.050MM
8. GERBER DATA SUPPLIED IN RS-274X FORMAT.
9. INTERPRET GERBER LAYERS AS FOLLOWS:
 M1 - TOP COMPONENT SIDE METALIZATION - 100 OHM DIFFERENTIAL IMPEDANCE
 M2 - INNER LAYER METAL
 M3 - INNER LAYER METAL - 100 OHM DIFFERENTIAL IMPEDANCE
 M4 - BOTTOM LAYER METAL - 100 OHM DIFFERENTIAL IMPEDANCE
 S1 - SOLDERMASK LAYER 1
 S4 - SOLDERMASK LAYER 4
 DRILL - THRU HOLE MECHANICAL DRILL
 P1 - SOLDER PASTE TOP COMPONENT SIDE (LAYER 1)
 P4 - SOLDER PASTE BOTTOM COMPONENT SIDE (LAYER 4)
 PCB - PCB OUTLINE
 L1 - LEGEND LAYER 1 (TOP COMPONENT SIDE)
 L4 - LEGEND LAYER 4 (BOTTOM COMPONENT SIDE)
10. MODIFICATION OF ARTWORK REQUIRES LINEAR TECHNOLOGY AUTHORIZATION.
11. VENDOR TO SUPPLY PANELIZED PCB'S IN A 3X2 OR 3X3 MATRIX. SEE DETAIL "A".
12. CROSS-SECTION OF PCB MUST BE NOT BE ALTERED. SEE SHEET 12 FOR EXACT CONSTRUCTION. REQUIRED IMPEDANCES WILL BE ACHIEVED BY PCB MFG. INHERENT TO THE DESIGN.



CUSTOMER NOTICE			
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CONTRACT NO.	APPROVALS	1530 McCarty Blvd Milpitas, CA 95035 Phone: (408) 432-1899 Fax: (408) 432-1999 LTC Confidential - For Customer Use Only	
PCB DES. GRIFITTS	ENG. D. STUETZLE		
THIS CIRCUIT IS PROPRIETARY TO LINEAR TECHNOLOGY AND SUPPLIED FOR USE WITH LINEAR TECHNOLOGY PARTS.		TITLE: SCHEMATIC	DATE:
14-Bit, 125 Msps Quad ADC with Integrated Drivers		LTM18012-AB DEMO CIRCUIT DC1732B	Monday, December 12, 2011
SIZE	IC NO.	SHEET	REV
B		15 OF 15	0